

Patent claims

1. A metal support for the bonding of electrical or optoelectronic components with a multiplicity of contact legs, that can respectively be connected to one end of a bonding wire for the bonding of a component at a bonding region, comprising at least one electrically nonconducting structure that mechanically interconnects at least two contact legs.
2. The metal support as claimed in claim 1, wherein the nonconducting structure comprises an injection-moldable plastic material, with which at least two contact legs are encapsulated.
3. The metal support as claimed in claim 1, wherein the nonconducting structure comprises at least one web that respectively interconnects at least two contact legs.
4. The metal support as claimed in claim 3, wherein the web runs substantially perpendicularly to the longitudinal direction of the contact legs.
5. The metal support as claimed in claim 1, wherein at least most of the bonding regions of the contact legs are arranged in a region at the ends of the contact legs that lie adjacent a component to be bonded.
6. The metal support as claimed in claim 1, wherein the nonconducting structure comprises a number of web-shaped structures present next to one another or parallel to one another or offset from one another.

7. The metal support as claimed in claim 6, wherein the web-shaped structures are of different lengths.

5 8. The metal support as claimed in claim 1, wherein the thermal expansion of the nonconducting structure is adapted to the thermal expansion of an encapsulating compound with which the metal support and the component are encapsulated after assembly has been completed.

10 9. A leadframe, comprising:
a receiving pad for placement of an electrical or optoelectronic component thereon;
a plurality of electrically conducting leadframe
15 legs each having a first end extending toward the receiving pad, and a second end extending away therefrom; and
an electrically nonconducting structure traversing and mechanically interconnecting at least two of the
20 leadframe legs.

10. The leadframe of claim 9, further comprising a bonding pad region at the first end of each of the plurality of lead frame legs.

25 11. The leadframe of claim 9, further comprising a bonding pad region located near the first end of each of the plurality of lead frame legs, wherein the bonding pad regions of the at least two leadframe legs interconnected
30 by the nonconducting structure are located between the first end and the nonconducting structure.

12. The leadframe of claim 9, wherein the nonconducting structure comprises an injection-moldable plastic material.

5 13. The leadframe of claim 12, wherein the plastic material consists of polybutylene terephthalate.

10 14. The leadframe of claim 9, wherein the nonconducting structure comprises at least one web that respectively interconnects at least two leadframe legs.

15 15. The leadframe of claim 14, wherein the web runs substantially perpendicularly to the longitudinal direction of the leadframe legs.

16 16. The metal support as claimed in claim 9, wherein the nonconducting structure comprises a number of web-shaped structures present next to one another or parallel to one another or offset from one another.

20 17. The leadframe of claim 16, wherein the web-shaped structures are of different lengths.

25 18. The leadframe of claim 9, wherein the thermal expansion of the nonconducting structure is adapted to the thermal expansion of an encapsulating compound with which the leadframe and the component are encapsulated after assembly has been completed.